IN THE CLAIMS

Please amend the claims as follows:

Claims 1-15 (Canceled).

Claim 16 (Previously Presented) A bistable MEMS microswitch produced on a substrate and configured to electrically connect ends of at least two conductive tracks, including a beam suspended above a surface of the substrate, wherein the beam is embedded at ends thereof and is subjected to compressive stress when the beam is in a non-deformed position, the beam including an electrical contact-forming mechanism to produce a lateral connection with ends of the at least two conductive tracks when the beam is deformed, the microswitch comprising:

means for actuating the beam to place the beam either in a first deformed position corresponding to a first stable state, or in a second deformed position corresponding to a second stable state, the second deformed position opposing the first deformed position, wherein

the microswitch is activated to urge the beam from an initial, non-deformed position to connect the electrical contact-forming mechanism to ends of the at least two conductive tracks.

Claim 17 (Previously Presented) A microswitch according to claim 16, wherein the microswitch is a dual microswitch, and the first deformed position corresponds to connection of ends of two first conductive tracks, and the second deformed position corresponds to connection of ends of two second conductive tracks.

Claim 18 (Previously Presented) A bistable MEMS microswitch produced on a substrate and configured to electrically connect ends of at least two conductive tracks, including a beam suspended above a surface of the substrate, wherein the beam is embedded at ends thereof and is subjected to compressive stress when the beam is in a non-deformed position, the beam including an electrical contact-forming mechanism to produce a lateral connection with ends of the at least two conductive tracks when the beam is deformed, the microswitch comprising:

means for actuating the beam to place the beam either in a first deformed position corresponding to a first stable state, or in a second deformed position corresponding to a second stable state, the second deformed position opposing the first deformed position, wherein

the microswitch is a single microswitch and is activated to urge the beam from an initial, non-deformed position to the first deformed position to connect the electrical contact-forming mechanism to ends of the at least two conductive tracks, and the second deformed position corresponds to an absence of a connection.

Claim 19 (Previously Presented) A microswitch according to claim 16, wherein the beam is made of a dielectric or semiconductor material and the electrical contact-forming mechanism includes an electrically conductive pad integrated into the beam.

Claim 20 (Previously Presented) A microswitch according to claim 19, wherein the means for actuating the beam includes thermal actuators using a bimetal effect.

Claim 21 (Previously Presented) A microswitch according to claim 20, wherein each thermal actuator includes a block of thermally conductive material in contact with an electrical resistance.

Claim 22 (Previously Presented) A microswitch according to claim 19, wherein the means for actuating the beam includes means for implementing electrostatic forces.

Claim 23 (Previously Presented) A microswitch according to claim 19, wherein the means for actuating the beam includes thermal actuators using a bimetal effect and means for implementing electrostatic forces.

Claim 24 (Previously Presented) A microswitch according to claim 16, wherein the beam is made of an electrically-conductive material.

Claim 25 (Previously Presented) A microswitch according to claim 24, wherein the means for actuating the beam includes means for implementing electrostatic forces.

Claim 26 (Currently Amended) A microswitch according to claim 16, wherein the electrical contact-forming ~~means~~ mechanism is configured to be embedded between the ends of the conductive tracks to be connected.

Claim 27 (Previously Presented) A microswitch according to claim 26, wherein the ends of the conductive tracks are flexible and conform to a deformation profile of the electrical contact-forming mechanism during a connection.

Claim 28 (Previously Presented) A microswitch according to claim 16, further comprising:

release spring-forming means for controlling a value of the compressive stress for at least one of the embedded ends of the beam.

Claim 29 (Previously Presented) A microswitch according to claim 16, wherein the electrical contact-forming mechanism provides an ohmic contact.

Claim 30 (Previously Presented) A microswitch according to claim 16, wherein the electrical contact-forming mechanism provides a capacitive contact.